

What is claimed is:

1. An electronic device comprising:

a substrate on which an interconnect pattern is formed;

5 a chip component having a first surface on which an electrode is formed and a second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate;

an insulating section formed of a resin and provided adjacent to the chip component; and

10 an interconnect which is formed to extend from above the electrode, over the insulating section and to above the interconnect pattern.

2. The electronic device as defined by claim 1,

wherein a side surface of the chip component is inclined to descend in an outward direction from the first surface.

3. The electronic device as defined by claim 1,

wherein the chip component has a step in an edge portion of the chip component.

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4. The electronic device as defined by claim 1,

wherein the insulating section is formed so that part of the insulating section overlays the first surface.

25 5. The electronic device as defined by claim 1,

wherein the insulating section is formed so that part of the insulating section does not overlay the first surface.

6. The electronic device as defined by claim 1,
wherein the insulating section has a portion higher than the first surface.

5 7. The electronic device as defined by claim 1, further comprising:
a connection layer that connects the chip component with the substrate.

8. The electronic device as defined by claim 7,
wherein the connection layer is formed of the same material as the insulating
10 section.

9. The electronic device as defined by claim 7,
wherein the connection layer is formed of a material different from a material of
the insulating section.

15 10. An electronic device comprising:
a substrate on which an interconnect pattern is formed;
a chip component having a first surface on which an electrode is formed and a
second surface opposite to the first surface, the chip component being mounted in such
20 a manner that the second surface faces the substrate;
an insulating section provided adjacent to the chip component and having an
inclined surface descending in an outward direction from the chip component; and
an interconnect which is formed to extend from above the electrode, over the
insulating section and to above the interconnect pattern.

25 11. The electronic device as defined by claim 10,
wherein the inclined surface is a depressed surface.

12. The electronic device as defined by claim 10,
wherein the inclined surface is a projected surface.

5 13. The electronic device as defined by claim 10,
wherein the insulating section is formed so that part of the insulating section
overlays the first surface.

14. The electronic device as defined by claim 10,
10 wherein the insulating section is formed so that part of the insulating section
does not overlay the first surface.

15. The electronic device as defined by claim 10,
wherein the insulating section has a portion higher than the first surface.
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16. The electronic device as defined by claim 10, further comprising:
a connection layer that connects the chip component with the substrate.

17. The electronic device as defined by claim 16,
20 wherein the connection layer is formed of the same material as the insulating
section.

18. The electronic device as defined by claim 16,
wherein the connection layer is formed of a material different from a material of
25 the insulating section.

19. A method of manufacturing an electronic device, the method comprising :

mounting a chip component having an electrode on a substrate on which an interconnect pattern is formed, in such a manner that a second surface faces the substrate, the electrode being formed on a first surface and the second surface being opposite to the first surface;

5 forming an insulating section of a resin adjacent to the chip component; and
 forming an interconnect in such a manner as to extend from above the electrode, over the insulating section and to above the interconnect pattern.

20. The method of manufacturing an electronic device as defined by claim 19,
10 wherein the interconnect is formed of a dispersant including electrically conductive particles.

21. The method of manufacturing an electronic device as defined by claim 20,
 wherein the step of forming the interconnect includes ejecting the dispersant
15 including the electrically conductive particles over the electrode, the insulating section and the interconnect pattern.

22. The method of manufacturing an electronic device as defined by claim 19,
 wherein the step of mounting the chip component on the substrate includes
20 interposing an adhesive between the substrate and the chip component.

23. The method of manufacturing an electronic device as defined by claim 22,
 wherein an insulating adhesive is used as the adhesive, and
 wherein the adhesive is pressed out from between the substrate and the chip
25 component to a region adjacent to the chip component, to form the insulating section from the adhesive.

24. The method of manufacturing an electronic device as defined by claim 22,
wherein the step of forming the insulating section includes providing a material
to form the insulating section besides the adhesive.

5 25. A method of manufacturing an electronic device, the method comprising :
mounting a chip component having an electrode on a substrate on which an
interconnect pattern is formed, in such a manner that a second surface faces the
substrate, the electrode being formed on a first surface and the second surface being
opposite to the first surface;

10 forming an insulating section of a resin adjacent to the chip component in such a
manner that the insulating section has an inclined surface descending in an outward
direction from the chip component; and

forming an interconnect in such a manner as to extend from above the electrode,
over the insulating section and to above the interconnect pattern.

15 26. The method of manufacturing an electronic device as defined by claim 25,
wherein the interconnect is formed of a dispersant including electrically
conductive particles.

20 27. The method of manufacturing an electronic device as defined by claim 26,
wherein the step of forming the interconnect includes ejecting the dispersant
including the electrically conductive particles over the electrode, the insulating section
and the interconnect pattern.

25 28. The method of manufacturing an electronic device as defined by claim 25,
wherein the step of mounting the chip component on the substrate includes
interposing an adhesive between the substrate and the chip component.

29. The method of manufacturing an electronic device as defined by claim 28,
wherein an insulating adhesive is used as the adhesive, and
wherein the adhesive is pressed out from between the substrate and the chip
5 component to a region adjacent to the chip component, to form the insulating section
from the adhesive.

30. The method of manufacturing an electronic device as defined by claim 28,
wherein the step of forming the insulating section includes providing a material
10 to form the insulating section besides the adhesive.

31. A circuit board on which an electronic device as defined in claim 1 is mounted.

32. A circuit board on which an electronic device as defined in claim 10 is mounted.
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33. An electronic instrument having an electronic device as defined in claim 1.

34. An electronic instrument having an electronic device as defined in claim 10.